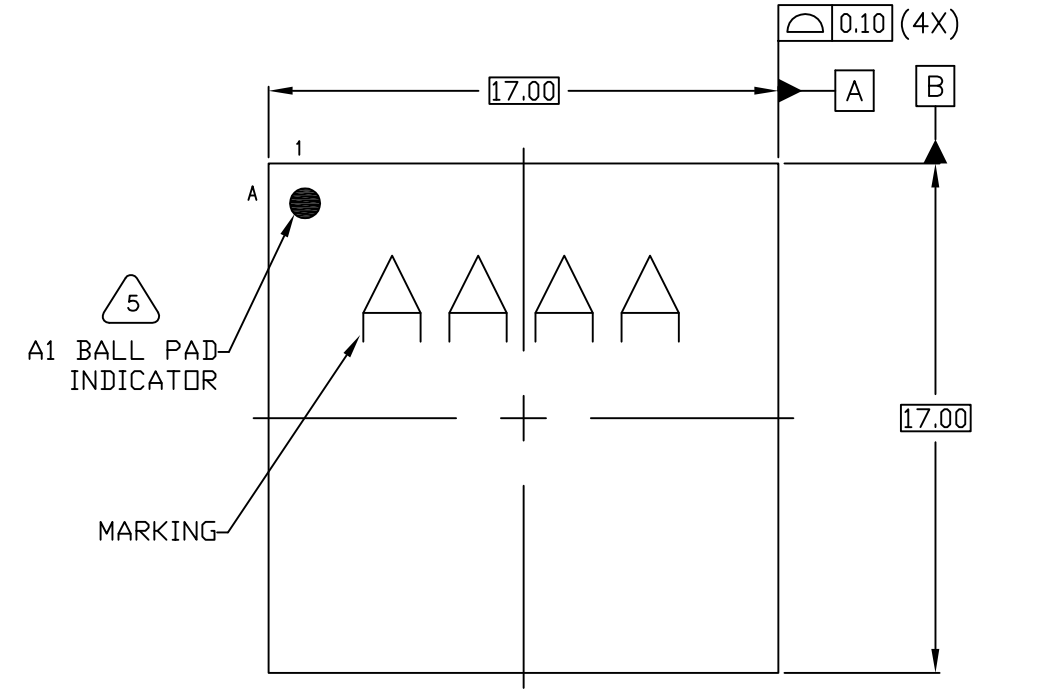
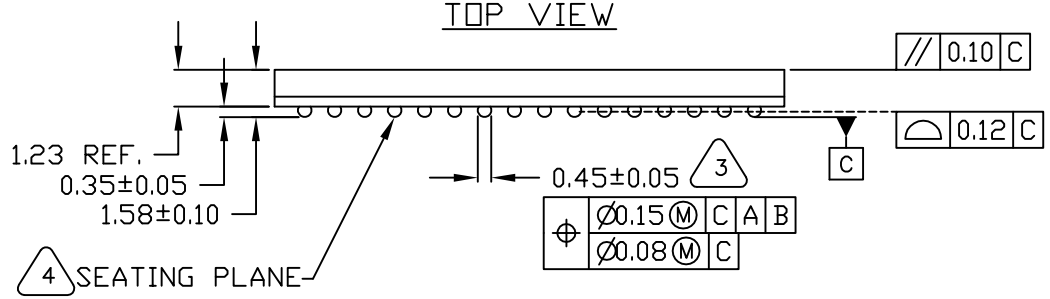
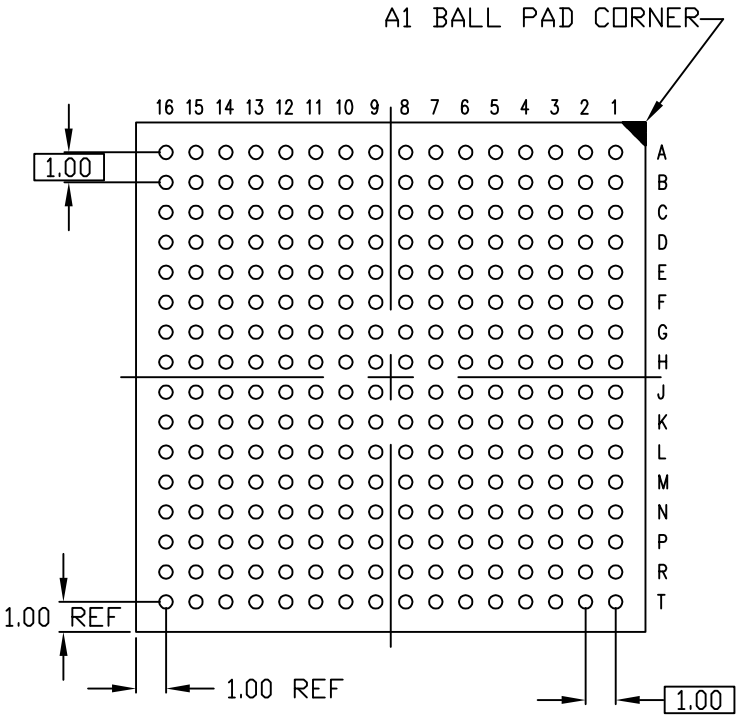


TOP VIEW



SIDE VIEW



BOTTOM VIEW
(BALL SIDE)

NOTES:

1. DIMENSION IS MM.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM.
3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. A1 BALL PAD CORNER I.D.
6. MARKING SHOWN IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
7. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.
8. PACKAGE CODES: X25677-11 & X25677-14

—DRAWING NOT TO SCALE—

MAXIM

TITLE:
PACKAGE OUTLINE,
256 BALLS CSBGA, 17x17x1.58mm

APPROVAL	DOCUMENT CONTROL NO.	REV.	
EDEN CHEN 03/11/10	21-0465	B	1/1